

Product Change Notification - ASER-27VHSG893

Date:

14 Jan 2020 Product Category: Ethernet Switches Affected CPNs:

7

Notification subject:

CCB 3867 Final Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8842 device family available in 100L LFBGA (9x9x1.38 mm) package. Notification text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel KSZ8842 device family available in 100L LFBGA (9x9x1.38 mm) package.

Pre Change:

Assembled at OSE assembly site using 2300 die attach and E770 molding compound.

Post Change:

Assembled at ASE assembly site using 2100 die attach and KE-G1250NAS molding compound.

Pre and Post Change Summary:

		Pre Change	Post Change				
Assembly Site		Orient Semiconductor	Advanced Semiconductor				
		Electronics, Ltd (OSE)	Engineering, Inc. (ASE)				
Wire material		Au	Au				
Die attach material		2300	2100				
Molding compound material		E770	KE-G1250NAS				
	Core	HL832NX	HL832NX				
Substrate	Solder Mask	AUS308	AUS308				
material	Solder Mask Thickness	25 ± 10µm	30 ± 10µm				
Solder Ball		SAC305	SAC305				



None.

Change Impact:

None.

Reason for Change:

To improve manufacturability by qualifying ASE as a new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 17, 2020 (date code: 2008)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2019					January 2020				February 2020					
Workweek	27	28	29	30	31	>	1	2	3	4	5	6	7	8	9
Initial PCN Issue Date		Х													
Qual Report Availability									Х						
Final PCN Issue Date									Х						
Estimated														\mathbf{v}	
Implementation Date														^	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

July 11, 2019: Issued initial notification.

July 15, 2019: Replaced inaccurate qualification plan with the correct document. Reissued initial notification.

January 14, 2019: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 17, 2020. Updated the Subject and Description to add the affected device families.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.



Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8842-PMBL KSZ8842-PMBL-AM KSZ8842-PMBL-AM-TR KSZ8842-PMBL-TR